g GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-GED-DS3810BFDA**

Test Procedure for a BF EXC Snubber assembly

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	G. Chandler	1/31/2013
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PREPARED BY	REVIEWED BY	REVIEWED BY	QUALITY APPROVAL
G. Chandler			Charlie Wade
DATE	**DATE**	**DATE**	**DATE**
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1. SCOPE

1.1 This is a functional testing procedure for a BF EXC Snubber assembly.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning
4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
4.2 Equipment Inspection
4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
4.2.1.1 Wires - broken, cracked, or loosely connected
4.2.1.2 Terminal strips / connectors - broken or cracked
4.2.1.3 Components - visually damaged
4.2.1.4 Capacitors - bloated or leaking
4.2.1.5 Solder joints - damaged or cold
4.2.1.6 Circuit board - burned or de-laminated
4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)

6. Modifications/Upgrades

6.1 Fill out if applicable.

7. Testing Process

7.1 Testing Procedure

7.1.1 Using an ohmmeter verify resistance between the following points.

7.1.1.1 J1 to J2= < 1ohm

7.1.1.2 J1 to J3 = open after capacitor charge.

7.1.1.3 J3 to J5 = 20 ohms +/- 10%

7.1.1.4 J4 to J5= 20 ohms +/- 10%

7.1.2 Using a capacitance meter verify capacitor measures .25uf +/- 20%, (Skip this step if the card you are testing is a DS3800NPCC).

7.1.3 Visually inspect MOVs on the card for cracks, burns or other deformities. Also inspect solder connections, especially on stab on connectors as these have a tendency to break.

7.2 ***TEST COMPLETE ***

8. Notes

8.1 None at this time.

9. Attachments

9.1 None at this time.